

## **AMENDMENTS TO THE SPECIFICATION**

Please insert the following new heading and new paragraph on page 1 just before the heading “BACKGROUND OF THE INVENTION”.

### **CROSS-REFERENCE TO RELATED APPLICATIONS**

Pursuant to 35 U.S.C. § 119(a), this application claims the benefit of earlier filing date and right of priority to Korean Application No. 04879/2003 filed January 24, 2003 the contents of which are hereby incorporated by reference herein in its entirety.

Please replace the paragraph starting on page 8, line 25 with the following:

First, the sensor chip 100 includes a plurality of material sensing sensors arranged in a lattice form. That is, a plurality of materials can be simultaneously measured through the plurality of material sensing sensors 101, and the plurality of material sensing sensors 101 are constructed in one sensor chip 100. The sensor chip ~~[[10]]~~ 100 is detachably attached to the sensor chip package, so that the disposable sensor chip 100 can be easily replaced.

Please replace the paragraph starting on page 11, line 9 with the following:

The common lower electrode 3 is formed on the lower membrane layer ~~[[2-2-2]]~~ 2-2 formed at a lower surface of the substrate 1, and commonly used by the pair of TFBARs (the measurement TFBAR and the reference TFBAR).